

Electronic Patent Application Fee Transmittal				
Application Number:	10537509			
Filing Date:	30-Nov-2005			
Title of Invention:	Method for cutting semiconductor substrate			
First Named Inventor/Applicant Name:	Fumitsugu Fukuyo			
Filer:	Joseph John Buczynski/Towanna Bolling			
Attorney Docket Number:	46884-5388 (211285)			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
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Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180